

Title (en)  
COPPER ALLOY FOR ELECTRONIC AND ELECTRICAL EQUIPMENT, COPPER ALLOY PLATE STRIP FOR ELECTRONIC AND ELECTRICAL EQUIPMENT, COMPONENT FOR ELECTRONIC AND ELECTRICAL EQUIPMENT, TERMINAL, BUSBAR, AND MOVABLE PIECE FOR RELAYS

Title (de)  
KUPFERLEGIERUNG FÜR ELEKTRONISCHE/ELEKTRISCHE VORRICHTUNGEN, KUPFERLEGIERUNGSBAND FÜR ELEKTRONISCHE UND ELEKTRISCHE VORRICHTUNGEN, KOMPONENTE FÜR ELEKTRONISCHE UND ELEKTRISCHE VORRICHTUNG, ENDGERÄT, SAMMELSCHIENE UND BEWEGLICHES TEIL FÜR RELAIS

Title (fr)  
ALLIAGE DE CUIVRE POUR ÉQUIPEMENT ÉLECTRONIQUE ET ÉLECTRIQUE, BANDE PLATE EN ALLIAGE DE CUIVRE POUR ÉQUIPEMENT ÉLECTRONIQUE ET ÉLECTRIQUE, COMPOSANT POUR ÉQUIPEMENT ÉLECTRONIQUE ET ÉLECTRIQUE, TERMINAL, BARRE OMNIBUS ET PIÈCE MOBILE POUR RELAIS

Publication  
**EP 3438298 A4 20191211 (EN)**

Application  
**EP 17775233 A 20170329**

Priority  

- JP 2016069080 A 20160330
- JP 2017063418 A 20170328
- JP 2017012914 W 20170329

Abstract (en)  
[origin: EP3438298A1] Provided is a copper alloy for electronic and electrical equipment including: 0.15 mass% or greater and less than 0.35 mass % of Mg; 0.0005 mass% or greater and less than 0.01 mass% of P; and a remainder which is formed of Cu and unavoidable impurities, in which a conductivity is greater than 75% IACS, and an average number of compounds containing Mg and P with a particle diameter of 0.1 μm or greater is 0.5 pieces/μm<sup>2</sup> or less in observation using a scanning electron microscope.

IPC 8 full level  
**C22C 9/00** (2006.01); **C22F 1/00** (2006.01); **C22F 1/08** (2006.01); **H01B 1/02** (2006.01)

CPC (source: EP KR US)  
**C22C 9/00** (2013.01 - EP KR US); **C22C 9/02** (2013.01 - US); **C22F 1/002** (2013.01 - EP US); **C22F 1/08** (2013.01 - EP KR US); **H01B 1/02** (2013.01 - KR); **H01B 1/026** (2013.01 - EP US); **H01B 5/02** (2013.01 - KR); **H01H 50/14** (2013.01 - KR); **H01H 50/56** (2013.01 - KR); **H01R 4/58** (2013.01 - KR); **H01R 13/03** (2013.01 - KR)

Citation (search report)  

- [A] JP 2014047378 A 20140317 - MITSUBISHI SHINDO KK
- [A] US 2014209221 A1 20140731 - KUMAGAI JUN-ICHI [JP], et al
- [A] JP H05311283 A 19931122 - MITSUBISHI SHINDO KK
- [A] JP 2015045083 A 20150312 - MITSUBISHI MATERIALS CORP
- [A] JP 2014025089 A 20140206 - MITSUBISHI SHINDO KK
- See references of WO 2017170699A1

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DOCDB simple family (publication)  
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DOCDB simple family (application)  
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